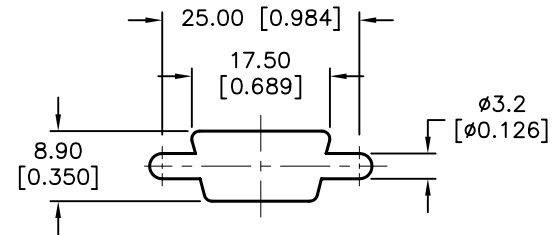
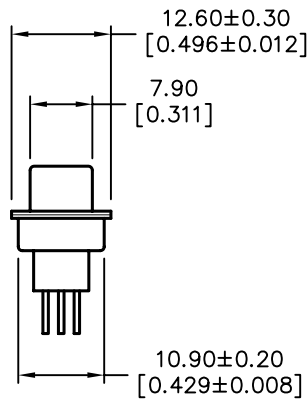
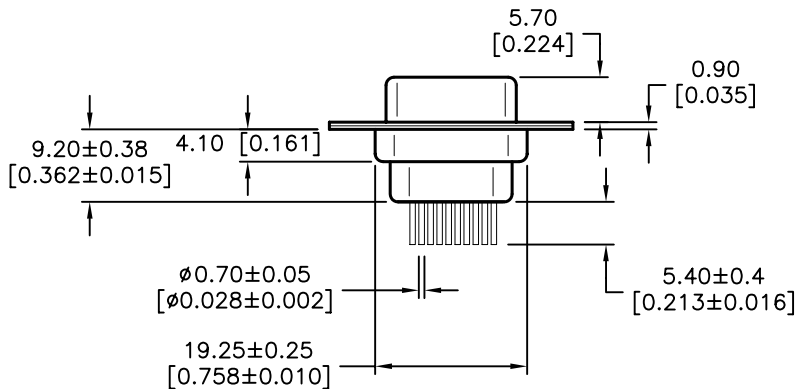
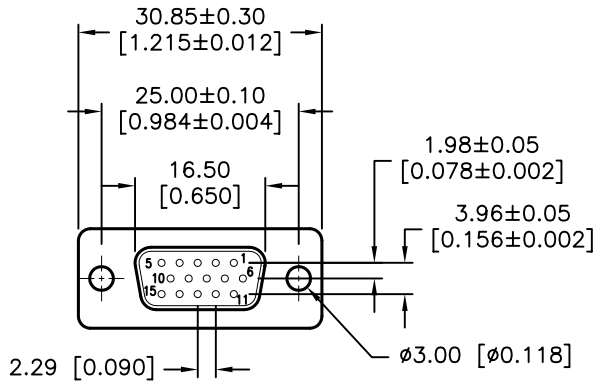
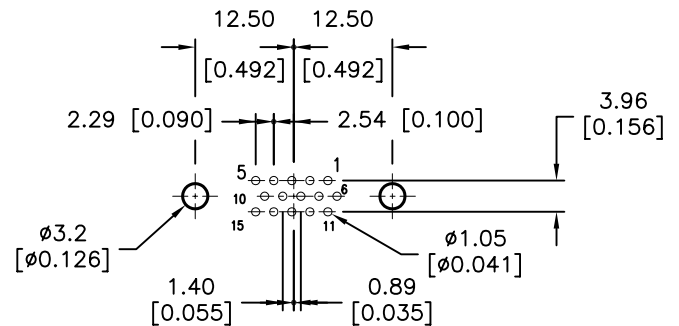


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				DCP #	REV	DESCRIPTION	DRAWN	DATE	CHECKD	DATE	APPRVD	DATE
				1876	A	RELEASED	EO	07/25/06	SA	07/25/06	HO	07/25/06



PANEL CUTOUT



PCB LAYOUT

Specifications:

1. Shell: Steel, Tin Plated
2. Insulator: PBT +30% Fiber-Glass, Black
UL94V-0 Rated
3. Contact: Brass, Stamped-Pin, Gold

DISCLAIMER: ALL STATEMENTS AND TECHNICAL INFORMATION CONTAINED HEREIN ARE BASED UPON INFORMATION AND/OR TESTS WE BELIEVE TO BE ACCURATE AND RELIABLE. SINCE CONDITIONS OF USE ARE BEYOND OUR CONTROL, THE USER SHALL DETERMINE THE SUITABILITY OF THE PRODUCT FOR THE INTENDED USE AND ASSUME ALL RISK AND LIABILITY WHATSOEVER IN CONNECTION THEREWITH.	TOLERANCES: Unless Otherwise Specified .X ±0.35 [0.014] .XX ±0.15 [0.006]	DRAWN BY:	DATE:	DRAWING TITLE:			
		EKLAS ODISH	07/25/06	15 Pin High-Density S-Sub DIP Socket			
		CHECKED BY:	DATE:	SIZE	DWG. NO.	ELECTRONIC FILE	REV
		SAMI ALNADI	07/25/06	A	SPC15408	79K4990.DWG	A
		APPROVED BY:	DATE:	SCALE: NTS		U.O.M.: mm [INCHES]	SHEET: 1 OF 1
		HISHAM ODISH	07/25/06				